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Amdt A  
11-29-03  
Article

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of Lee et al.  
Application No. Not Yet Assigned  
Filing Date November 16, 2001  
For A METHOD OF ASSEMBLING A SEMICONDUCTOR DEVICE PACKAGE

November 29, 2001

PRELIMINARY AMENDMENT A

TO THE ASSISTANT COMMISSIONER FOR PATENTS,

SIR:

Please enter the following amendments prior to examination of the above-referenced application:

IN THE CLAIMS:

Please amend claims 3, 4, and 8-12 as follows:

A'  
3. A method according to claim 1, wherein the semiconductor device package is a surface mount semiconductor device package.

4. A method according to claim 1, further comprising, after encapsulating the coated device/leadframe assembly, removing the coating from non-encapsulated portions of the leadframe.

A<sup>2</sup>  
8. A semiconductor device package according to claim 5, wherein the semiconductor device is attached to the first portion of the leadframe by an adhesive.